

SLG51002C - EVB

SLG51002C Power GreenPAK Evaluation Board R1.1

1. Install Go Configure™ Software Hub

Download and install the latest Go Configure™ Software Hub software from <u>https://www.renesas.com/software-tool/go-configure-software-hub</u>.

Ø Go Configure Software Hub Installing Go Configure Software Hub					
Go Configure Software Hub is Please wait	being installed.				
	< Back	Next >	Cancel		

3. Set Project Settings

Set desired voltages and other settings according to your project.

pecs	Informat	ion	General	Security				
perati	ng conditio	ns						
		Min.		Тур.		Max.		
VDD (<i>η</i> :	2.80	\$	3.80	\$	5.00	÷	0
VDDIC	M:	1.20	0	1.80	\$	5.00	÷.	0
Tempe	rature ("C):	-40	\$	25	:	85	\$	0

5. Prepare Development Board

Using external power supplies, apply 3.8 V to V_{DD} and 1.8 V to V_{DDIO} and CS pins. Insert the GreenPAK Serial Debugger (GSD) into the Evaluation Board for chip emulation.



2. Create a New Project

Start Go Configure™ Software Hub and select the SLG51002C device from the Power GreenPAK™ section.

	Software Tool	Part Family							
	м	м	SLC	510020	C			Eber.	
		General Date	Part Number	DS	VDO (V)	VDD2 (V)	Temperature (*C)	GPIjGPOjGPIO	
		area root.	SL651003V	Context up	2.80 to 5.00	1.20 to 5.00	-42.00 to 85.00	192.4	3x LDO (7
Recent	Recent		EE \$1.551000C	101	2.80 to 5.00		-42.00 to 25.00	10.5	Synchroni
		Analog MC	E \$1551001C	101	2.80 to 5.00		-40.00 to 85.00	190,5	Synchronic
			11 S1557002C	105					
	GreenPAK	HIDK	SU549957M	105	2.30 to 5.50		-40.00 to 85.00	1100	
	Dusigner	PHILIP C	\$1,540303M	105	2.50 to 5.50		42.00 to 85.00	192.6	
		Person Grace/PAC	BC 51,540387V	101	2.30 to 5.50		-40.00 to 85.00	190(5	
			BI 51545382V	105	2.30 to 5.50		-40.00 to 85.00	190(8	
			IN \$1,545387V	205	2.30 to 5.50		40.00 to 85.00	100/8	
		ActemptionAL	HILSUG40317M	EQE	1.71 to 5.50		40.00 is 85.00	10012	
	Activity of the	BR 01 0401 776.4	505	1714-5.55		41.00 23.00	100.5		
	FunguEPGA	forest/GA	Details [Source Inductions Audication mate Sources Actionals Contextus						
	Workshop	Pargari an							
			Package: WLCSP 25						
Application notes			Supported Developme • GreenPAK Serial • Pervo PAK Devel	Delwager (SLG4D)	NGSD) JS51002CTR Evaluati	on Socket			
			Description: SL651002 contains di moti-neil applications.	ght compact and c	ustomizable low dro	post regulators and is	designed for high perfor	mance carriera mediales i	ind other small
			There are three general p	surpose LEO HV; b	io high current LDO	HC, and three low vo	log: LEO LX.		
Datasheets			LDD HV and LDD HC an mode to meet high pow			ations, with wide ope	rating voltage ranges in a	id:Rien, LDO HC has a le	uit in Auto bypes
					and the second se		the second the second second	and the second second second	

4. Develop the Project

You are now ready to start developing using all available components including Power Sequencer, LDOs, LUTs, DFFs, DLYs, and much more.

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		- 	The latest of the	- 100	
Log III			They be have \$2.00		
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6. Emulate the Chip

Click the toolbar icon to start the Power GreenPAKTM Emulation Tool. Choose the GreenPAK Serial Debugger from the Development Platform Selector window. Press the Emulation button to load the project code onto the chip. At this point the chip will operate according to the project code. Press the Sync button to upload project changes to the chip. Emulation can be performed multiple times, even on programmed chips. Press the Emulation button again to exit the emulation mode.

Debugging controls	0
Debuggin	g Controls
	Change platform
GreenPAK Serial Debugger	Import configuration
Device: Auto detect	0
Emulation	Test Mode
Sync	
VDD: 2	1.80 V 👻



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